

ABSTRACT

**Method of fabricating through-connections in a substrate,
and substrate equipped with such connections**

The invention relates to the methods of fabricating conducting through-connections in a substrate, and the substrates equipped with such connections.

The method of fabricating conducting through-connections between the front face (2) and the rear face (3) of a substrate (1) consists:

- in hollowing into the substrate (1), from the rear-face (3) side, cavities (5) having a depth and a cross section which are defined so as to delimit studs (4) of defined cross section which are intended to provide for electrical conduction between the two faces (2, 3) and

- in filling in the cavities (5) with a dielectric material (7).

The substrate is equipped with conducting through-connections between its front face (2) and its rear face (3). The conducting connections are provided by way of studs (4) delimited by cavities (5) filled in with a dielectric material (7).

Application, in particular, to substrates used for the fabrication of microsensors.

FIGURE 5.